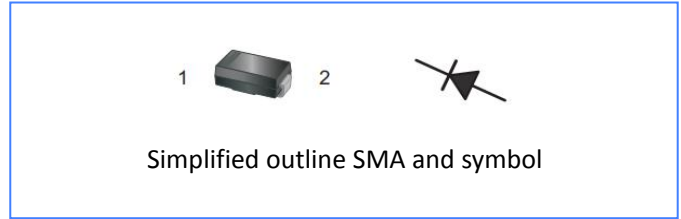


## S1A THRU S1M

### Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives



### Mechanical Data

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

### Pinning

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | Cathode     |
| 2   | Anode       |

### Absolute Maximum Ratings And Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Parameter  | Symbols         | S1A        | S1B | S1D | S1G | S1J | S1K | S1M  | Units              |
|--|-----------------|------------|-----|-----|-----|-----|-----|------|--------------------|
| Maximum Repetitive Peak Reverse Voltage  | $V_{RRM}$       | 50         | 100 | 200 | 400 | 600 | 800 | 1000 | V                  |
| Maximum RMS voltage  | $V_{RMS}$       | 35         | 70  | 140 | 280 | 420 | 560 | 700  | V                  |
| Maximum DC Blocking Voltage  | $V_{DC}$        | 50         | 100 | 200 | 400 | 600 | 800 | 1000 | V                  |
| Maximum Average Forward Rectified Current at $T_c = 125^\circ\text{C}$                                     | $I_{F(AV)}$     | 1          |     |     |     |     |     |      | A                  |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load                         | $I_{FSM}$       | 30         |     |     |     |     |     |      | A                  |
| Maximum Forward Voltage at 1 A   | $V_F$           | 1.1        |     |     |     |     |     |      | V                  |
| Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125^\circ\text{C}$ | $I_R$           | 5<br>50    |     |     |     |     |     |      | $\mu\text{A}$      |
| Typical Junction Capacitance <sup>(1)</sup>  | $C_j$           | 15         |     |     |     |     |     |      | pF                 |
| Typical Thermal Resistance <sup>(2)</sup>  | $R_{\theta JA}$ | 75         |     |     |     |     |     |      | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range  | $T_j, T_{stg}$  | -55 ~ +150 |     |     |     |     |     |      | $^\circ\text{C}$   |

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Rating And Characteristic Curves

Fig.1 Forward Current Derating Curve

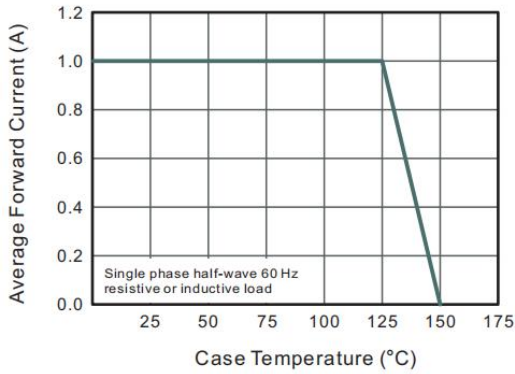


Fig.2 Typical Reverse Characteristics

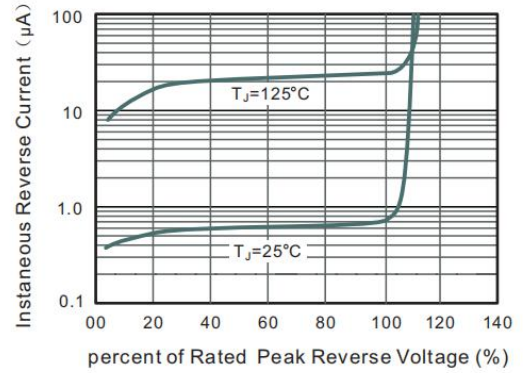


Fig.3 Typical Forward Characteristic

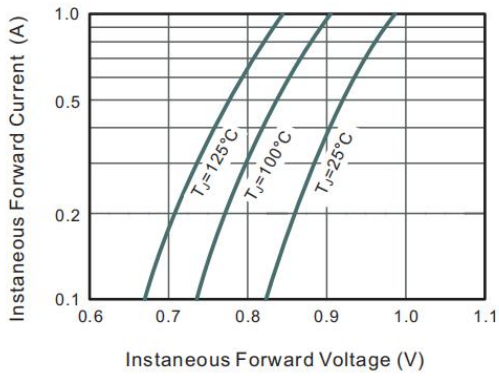


Fig.4 Typical Junction Capacitance

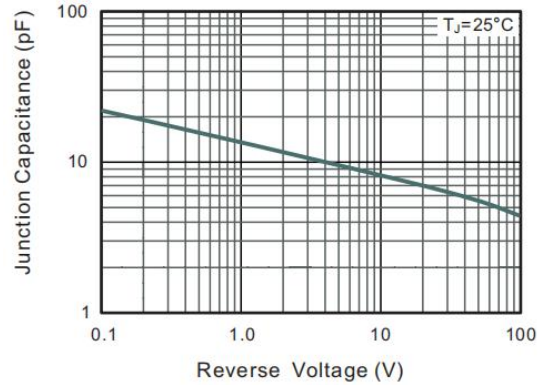
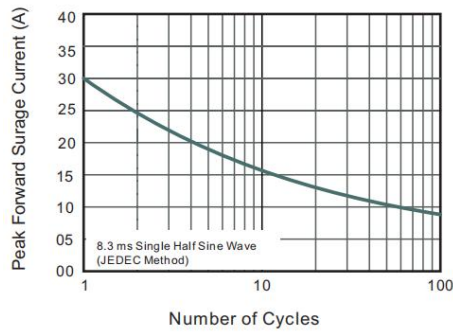


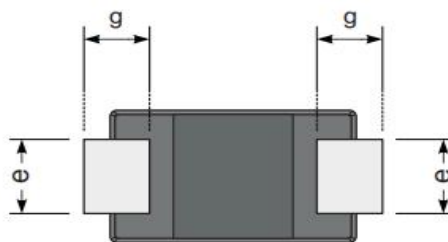
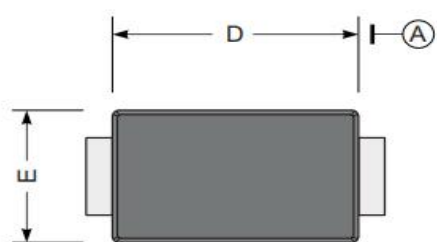
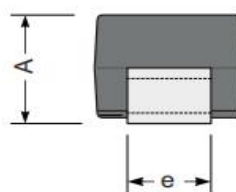
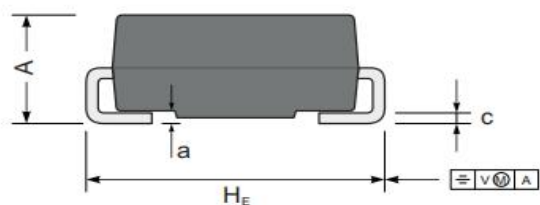
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



Package Outline

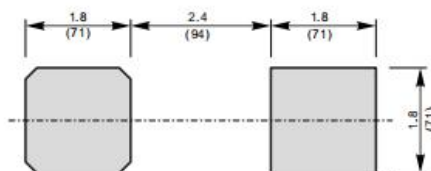
Plastic surface mounted package; 2 leads

SMA



| UNIT |     | A   | C    | D   | E   | e   | g   | H <sub>E</sub> | a   |
|------|-----|-----|------|-----|-----|-----|-----|----------------|-----|
| mm   | max | 2.2 | 0.31 | 4.5 | 2.7 | 1.6 | 1.5 | 5.2            | 0.3 |
|      | min | 1.9 | 0.15 | 4.0 | 2.3 | 1.3 | 0.9 | 4.7            |     |
| mil  | max | 87  | 12   | 181 | 106 | 63  | 59  | 205            | 12  |
|      | min | 75  | 6    | 157 | 91  | 51  | 35  | 185            |     |

The recommended mounting pad size



Unit :  $\frac{\text{mm}}{\text{(mil)}}$